



PATENT
Attorney Docket No.: COOL-00800

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)	Group Art Unit: 3753
Girish Upadhyia et al.)	Examiner:
Serial No.: 10/698,180)	<u>TRANSMITTAL LETTER</u>
Filed: October 30, 2003)	162 N. Wolfe Road
For: OPTIMAL SPREADER SYSTEM,)	Sunnyvale, CA 94086
DEVICE AND METHOD FOR)	(408) 530-9700
FLUID COOLED MICRO-SCALED)	Customer No.: 28960
HEAT EXCHANGE)	

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313

Sir:

Enclosed please find an Information Disclosure Statement and Form PTO-1449, including copies of the references contained thereon, for filing in the U.S. Patent and Trademark Office.

You will also find enclosed the associated Transmittals, Electronic Information Disclosure Statements, and United States Patent and Trademark Office Acknowledgment Receipts for the electronically filed Information Disclosure Statement (EFS ID #57478); (EFS ID #57479); (EFS ID #57481); and (EFS ID #57483) filed on March 19, 2004.

The Commissioner is hereby authorized to charge any additional fee or credit overpayment to our Deposit Account No. 08-1275. **An originally executed duplicate of this transmittal is enclosed for this purpose.**

Respectfully submitted,
HAVERSTOCK & OWENS LLP

Dated: 3/19/04

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CERTIFICATE OF MAILING (37 CFR § 1.8(a))

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HAVERSTOCK & OWENS LLP.
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For: **OPTIMAL SPREADER SYSTEM,
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) Group Art Unit: 3753

) Examiner:

) **INFORMATION DISCLOSURE**
) **STATEMENT**

) 162 N. Wolfe Road
) Sunnyvale, CA 94086
) (408) 530-9700

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Sir:

The citations listed below, copies attached, may be material to the examination of the above-identified application, and are therefore submitted in compliance with the duty of disclosure defined in 37 C.F.R. §§ 1.56 and 1.97. The Examiner is requested to make these citations of official record in this application.

United States Patents or Published Patent Applications have been filed electronically (EFS ID #57478); (EFS ID #57479); (EFS ID #57481); and (EFS ID #57483). Applicants have become aware of the following printed publication which may be material to the examination of this application:

- Chinese Publication No. CN 97212126.9;
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Respectfully submitted,
HAVERSTOCK & OWENS LLP

Dated: 3-19-04

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(37 CFR § 1.98(h))					
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Examiner:			Date Considered:		
EXAMINER: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.					

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use Several Sheets If Necessary)				Applicants: Girish Upadhyaya et al.	
				Filing Date: October 30, 2003	Group Art Unit: 3753
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Examiner:			Date Considered:		
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FORM PTO-1449
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Attorney Docket No.: COOL-00800

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Applicants: Girish Upadhyaya et al.

(37 CFR § 1.98(b))

Filing Date: October 30, 2003

Group Art Unit: 3753

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GO	David S. Shen et al., <u>Micro Heat Spreader Enhance Heat Transfer in MCMs</u> , 1995, IEEE Multi-Chip Module Conference, pages 189-194.
GP	S. Sasaki et al., <u>Optimal Structure for Microgrooved Cooling Fin for High-Power LSI Devices</u> , Electronic Letters, December 4, 1986, Vol 22, No. 25.
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ACKNOWLEDGEMENT RECEIPT**

Electronic Version 1.1

Stylesheet Version v1.1.1

Title of Invention	OPTIMAL SPREADER SYSTEM, DEVICE AND METHOD FOR FLUID COOLED MICRO-SCALED HEAT EXCHANGE										
Submission Type:	Information Disclosure Statement										
Application Number:	10/698180	*10/698180*									
EFS ID:	57478										
Server Response:	<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 15%;">Confirmation Code</th> <th>Message</th> </tr> </thead> <tbody> <tr> <td>ISVR1</td> <td>Submission was successfully submitted - Even if Informational or Warning Messages appear below, please do not resubmit this application</td> </tr> <tr> <td>ICON1</td> <td>9903</td> </tr> <tr> <td>ISYS5</td> <td>Filename= N/A BusinessRule= Validation System/Function Call Information. #Supporting Msg:Server unable to validate the Confirmaton/Application numbers at this time. They will be checked by PTO personnel later.</td> </tr> </tbody> </table>			Confirmation Code	Message	ISVR1	Submission was successfully submitted - Even if Informational or Warning Messages appear below, please do not resubmit this application	ICON1	9903	ISYS5	Filename= N/A BusinessRule= Validation System/Function Call Information. #Supporting Msg:Server unable to validate the Confirmaton/Application numbers at this time. They will be checked by PTO personnel later.
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ISYS5	Filename= N/A BusinessRule= Validation System/Function Call Information. #Supporting Msg:Server unable to validate the Confirmaton/Application numbers at this time. They will be checked by PTO personnel later.										
First Named Applicant:	Girish Upadhya										
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Page 2 of 2

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TRANSMITTAL							
Electronic Version v1.1 Stylesheet Version v1.1.0							
Title of Invention	OPTIMAL SPREADER SYSTEM, DEVICE AND METHOD FOR FLUID COOLED MICRO-SCALED HEAT EXCHANGE						
Application Number:	10/698180 *10/698180*						
Date:	2003-10-30						
First Named Applicant:	Girish Upadhyia						
Confirmation Number:	9903						
Attorney Docket Number:							
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Thomas B. Haverstock Registered Number: 32571</td><td>/tbh/</td><td>Attorney</td></tr></tbody></table>		Submitted by:	Elec. Sign.	Sign. Capacity	Thomas B. Haverstock Registered Number: 32571	/tbh/	Attorney
Submitted by:	Elec. Sign.	Sign. Capacity					
Thomas B. Haverstock Registered Number: 32571	/tbh/	Attorney					

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ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v1.8

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Title of
InventionOPTIMAL SPREADER SYSTEM, DEVICE AND METHOD FOR FLUID
COOLED MICRO-SCALED HEAT EXCHANGE

Application Number: 10/698180

10/698180

Confirmation Number: 9903

First Named Applicant: Girish Upadhyia

Attorney Docket Number:

Search string: (3654988 or 3817321 or 3823572 or 3923426 or 3929154 or 4109707 or 4194559 or 4248295 or 4312012 or 4450472 or 4485429 or 4516632 or 4561040 or 4567505 or 4573067 or 4664181 or 4866570 or 4868712 or 4894709 or 4896719 or 4908112 or 4938280 or 5009760 or 5016138 or 5057908 or 5058627 or 5070040 or 5083194 or 5088005 or 5096388 or 5099311 or 5099910 or 5125451 or 5131233 or 5203401 or 5218515 or 5219278 or 5232047 or 5239200 or 5263251 or 5274920 or 5309319 or 5317805 or 5325265 or 5336062 or 5380956 or 5383340 or 5427174 or 5436793 or 5459099).pn.

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Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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Date